



Features 特性

- High Thermal Conductivity
高导热
- Low Density 低密度
- High Reliability 高可靠性
- Automatic Dispensing
自动化点胶

Applications 产品应用

- Consumer Electronics 消费电子
- Communication Equipment
通讯设备
- Power Supply Controller
电源控制系统
- Smart Wearable Product
智能穿戴产品

Thermal TG0601LD 是一种具有高导热，低密度，低压缩应力和优异可靠性的单组份导热凝胶。其具有良好的弥合公差能力，适用于自动化点胶等应用场景。

Thermal TG0601LD is a kind of one-component thermal conductive gel with high thermal conductivity, low density, low compression stress and excellent reliability performance. The material provides good gap filling ability and could be used for automatic dispensing.

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Composition 主要成分	Silicone Filled with Thermal Powder 硅胶&导热粉体		—
Color 颜色	Violet 紫色	—	Visual 目视
Thermal Conductivity 导热系数	6.0	W/m·K	ASTM D5470
Flow Rate 流速	23	g/min	30cc EFD, 90Psi
Bond-line Thickness 界面结合厚度	0.175	mm	40Psi @ RT
Density 密度	2.70	g/cm ³	ASTM D792
Temperature Range 耐温范围	-40 - 150	°C	—
Breakdown Voltage 击穿强度	> 5.0	KV/mm	ASTM D149
Flame Rating 阻燃等级	V-0	—	UL 94
RoHS Compliance 合规性	YES	—	—
Shelf Life 保存期	6	month	25±5°C, ≤50% RH, 未启封

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

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